



PROCESS CHANGE NOTICE PCN0404 ADDITIONAL MOLD COMPOUND FOR TQFP 144 PACKAGE

Change Description:

The Sumitomo G700L mold compound is being added as additional mold compound choice for selected Altera® devices in thin quad flat pack (TQFP) 144 lead packages assembled by Amkor Technology Korea. Altera has successfully qualified this new mold compound and found it to meet the moisture rating requirements and reliability specifications for this package.

Reason for Change:

The Sumitomo G700L mold compound is offered as additional mold compound choice for this package due to improved performance and the ability to support Pb free and green package requirements. Altera currently uses the Sumitomo EME 7320 series mold compound for TQFP packages assembled by Amkor and other assembly sites.

Products Affected:

The list of selected TQFP 144 package devices affected by this change will be available on request.

Product Traceability and Transition Dates:

This change will be implemented beginning June 2004. The country of origin "Korea" marked on affected devices will distinguish those assembled with this new mold compound.

Contact:

For more information on this advisory or qualification report, please contact your local Altera sales representative or the Altera Customer Quality Engineering Department.